

S G S-THOMSON

TRIACS

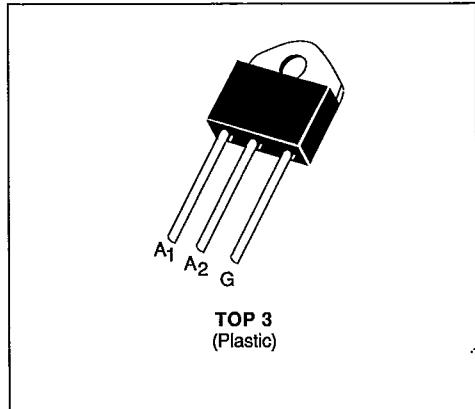
- GLASS PASSIVATED CHIP
- IGT SPECIFIED IN FOUR QUADRANTS
- INSULATING VOLTAGE 2500 VRMS
- UL RECOGNIZED (E81734)

DESCRIPTION

This new design of plastic insulated power triacs offers maximum efficiency with maximum ease of mounting.

ADVANTAGES

- NO TAPPING REQUIRED FOR FIXING
- EXCELLENT THERMAL IMPEDANCE AND HIGH RELIABILITY CONSTRUCTION

**ABSOLUTE RATINGS (limiting values)**

Symbol	Parameter	Value	Unit
$I_{T(RMS)}$	RMS on-state Current (360° conduction angle)	40	A
I_{TSM}	Non Repetitive Surge Peak on-state Current (T_i initial = 25 °C - Half sine wave)	$t = 8.3$ ms	A
		$t = 10$ ms	
I^2t	I^2t Value for Fusing	450	A^2s
di/dt	Critical Rate of Rise of on-state Current (1)	10	$A/\mu s$
		50	
T_{stg} T_j	Storage and Operating Junction Temperature Range	-40 to 125 -40 to 125	°C °C

Symbol	Parameter	BTA 41-					Unit
		200B	400B	600B	700B	800B	
V_{DRM}	Repetitive Peak off-state Voltage (2)	200	400	600	700	800	V

(1) $I_G = 1$ A $di/dt = 1 A/\mu s$ (2) $T_i = 125$ °C.**THERMAL RESISTANCES**

Symbol	Parameter	Value	Unit
$R_{th (j-a)}$	Junction to Ambient	50	°C/W
$R_{th (c-h)}$	Contact (case-heatsink) with Grease	0.2	°C/W
$R_{th (j-c)} DC$	Junction to Case for DC	1.2	°C/W
$R_{th (j-c)} AC$	Junction to Case for 360 ° Conduction Angle (F = 50 Hz)	0.9	°C/W

GATE CHARACTERISTICS (maximum values)

 $P_{GM} = 40 \text{ W}$ ($t_p = 10 \mu\text{s}$) $I_{GM} = 10 \text{ A}$ ($t_p = 10 \mu\text{s}$) $P_G(\text{AV}) = 1 \text{ W}$ $V_{GM} = 16 \text{ V}$ ($t_p = 10 \mu\text{s}$)

T-25-17

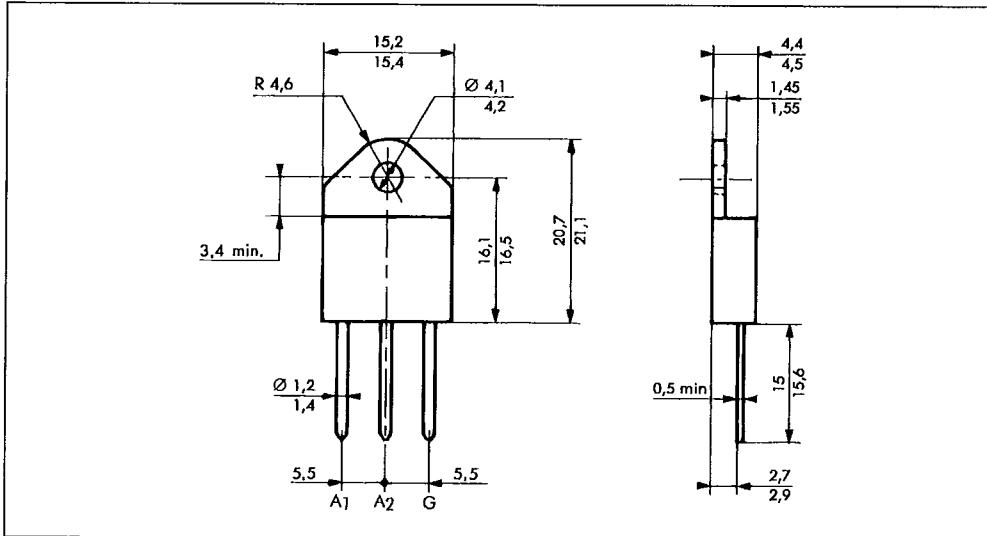
ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions	Quadrants	Min.	Typ.	Max.	Unit	
I_{GT}	$T_j = 25^\circ\text{C}$ $V_D = 12 \text{ V}$ $R_L = 33 \Omega$	I-II-III	1		50	mA	
	Pulse Duration > 20 μs	IV	1		100		
V_{GT}	$T_j = 25^\circ\text{C}$ $V_D = 12 \text{ V}$ $R_L = 33 \Omega$	I-II-III-IV			1.5	V	
Pulse Duration > 20 μs							
V_{GD}	$T_j = 125^\circ\text{C}$ $V_D = V_{DRM}$ $R_L = 3.3 \text{ k}\Omega$	I-II-III-IV	0.2			V	
I_{H^*}	$T_j = 25^\circ\text{C}$ $I_T = 500 \text{ mA}$ Gate Open			30	80	mA	
I_L	$T_j = 25^\circ\text{C}$ $V_D = 12 \text{ V}$ $I_G = 200 \text{ mA}$	I-II-III-IV			100	mA	
Pulse Duration > 20 μs							
V_{TM^*}	$T_j = 25^\circ\text{C}$ $I_{TM} = 60 \text{ A}$ $t_p = 10 \text{ ms}$				1.8	V	
I_{DRM^*}	$T_j = 125^\circ\text{C}$ V_{DRM} Specified				1.5	6	mA
dv/dt^*	$T_j = 125^\circ\text{C}$ Gate Open Linear Slope up to $V_D = 67\% V_{DRM}$			250		V/ μs	
$(dv/dt)_c^*$	$T_C = 75^\circ\text{C}$ $V_D = V_{DRM}$ $I_T = 60 \text{ A}$ $(di/dt)_c = 18 \text{ A/ms}$		5			V/ μs	
t_{gt}	$T_j = 25^\circ\text{C}$ $V_D = V_{DRM}$ $I_T = 60 \text{ A}$ $dI_G/dt = 10 \text{ A}/\mu\text{s}$	I-II-III-IV		2.5		μs	

* For either polarity of electrode A₂ voltage with reference to electrode A₁.

PACKAGE MECHANICAL DATA

TOP 3 Plastic



Cooling method : by conduction (method C)

Marking : type number

Weight : 5 g

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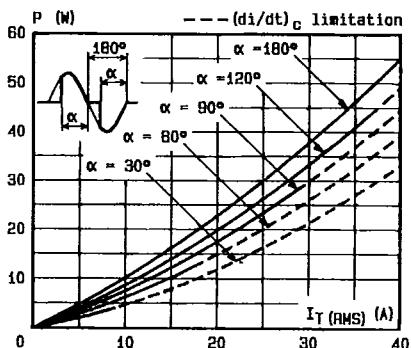


Fig.1 - Maximum mean power dissipation versus RMS on-state current ($f = 60$ Hz).

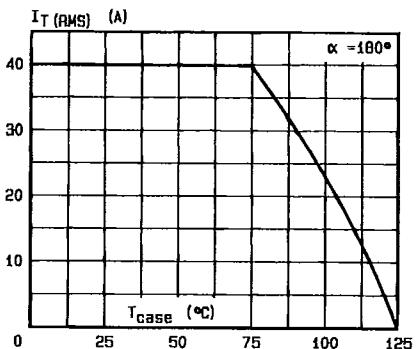


Fig.3 - RMS on-state current versus case temperature.

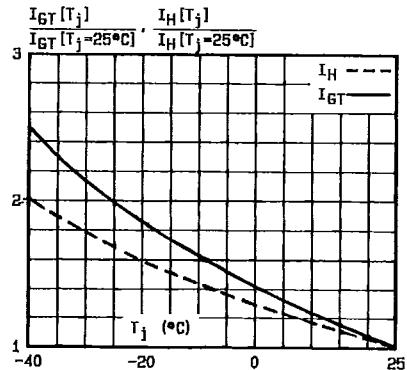


Fig.5 - Relative variation of gate trigger current and holding current versus junction temperature.

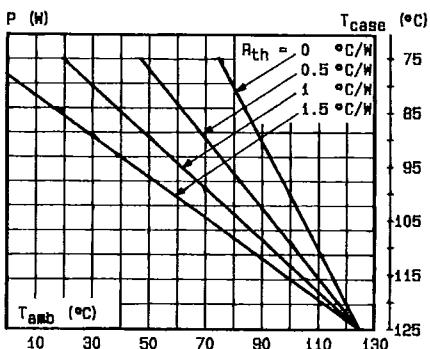


Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact.

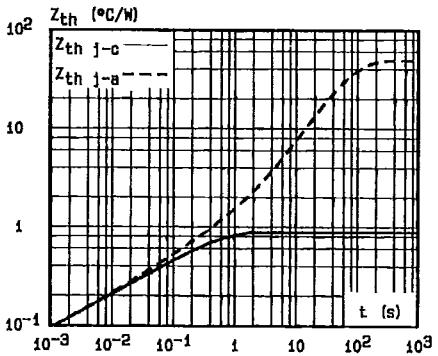


Fig.4 - Thermal transient impedance junction to case and junction to ambient versus pulse duration.

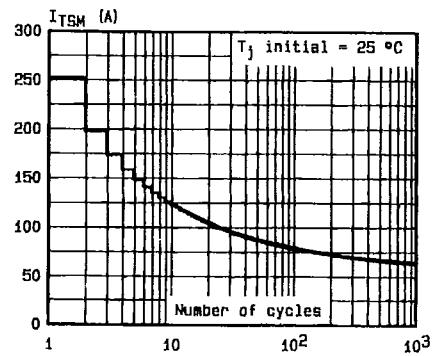


Fig.6 - Non repetitive surge peak on-state current versus number of cycles.

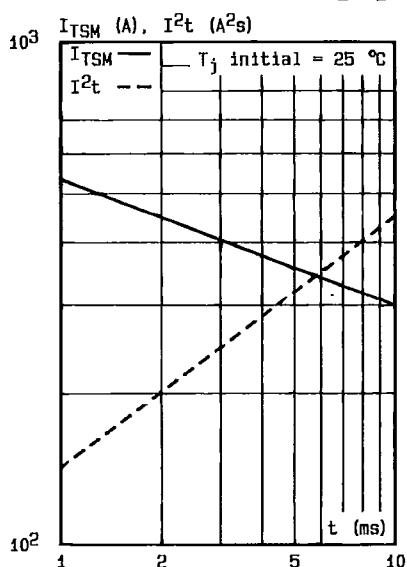


Fig.7 - Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10$ ms. and corresponding value of I^2t .

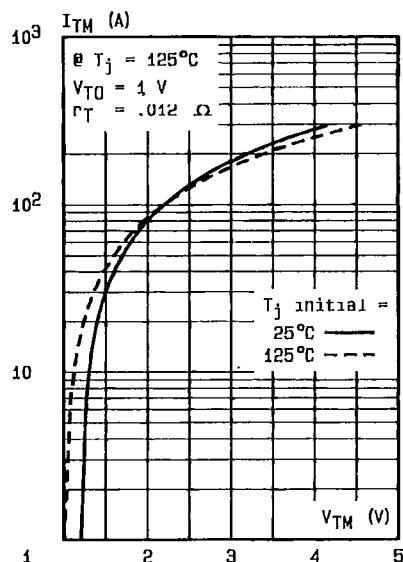


Fig.8 - On-state characteristics (maximum values).